Environmental Compliance Evaluation Report

Product Name : Server

Product Model : See Page 3

Report Number : SYBH(G)08140865

Reliability Laboratory of xFusion Digital Technologies Co., Ltd.

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Notice

1. The evaluation report is invalid if not marked with the signatures of the persons responsible for preparing and approving the report.

2. The evaluation report is invalid if there is any evidence of erasure and/or falsification.

3. The evaluation report is based on the quality and trustworthiness of the documents for materials, parts, and/or sub-assemblies provided by the suppliers. xFusion has established procedures to evaluate the documents in order to determine their quality and trustworthiness according to IEC 63000:2016 and EN IEC 63000: 2018.

4. The evaluation report, in part or in full, cannot be used for publicity and/or promotional purposes without prior written approval from the laboratory.

Applicant	:	xFusion Digital Technologies Co., Ltd.
Address	:	No. 99, Longhu Inner Ring North Road, Zhengzhou Area of China (Henan) Pilot Free Trade Zone, Henan Province, 450000, China
Manufacturer	:	Same as applicant
Address	:	Same as applicant
Product Name	:	Server
Product Model	:	2288 V8**********,FusionServer 2288 V8********** (where * can be 0-9, a-z, A-Z, - or Blank for marketing purpose)
Date of Sample Receiving	:	2025-10-13
Start Date of Evaluation	:	2025-10-13
End Date of Evaluation	:	2025-10-16

Evaluation Result :

Regulation/Directive	Conclusion
EU RoHS (2011/65/EU& (EU) 2015/863) & UK RoHS	**Comply**
SVHC in accordance with Article 59(1) of the Regulation (EC) No 1907/2006 (REACH)	**See Clause 5.1**
Regulation (EC) No 1907/2006 (REACH) Annex XVII	**Comply**
94/62/EC (Packaging and Packaging Waste) Article 11&Regulation (EU) 2025/40 (Packaging and Packaging Waste Regulation, PPWR) Article 5.4 & The Packaging (Essential Requirements) Regulations 2015	**Comply**
EU WEEE (2012/19/EU) ANNEX V & UK WEEE SCHEDULE 11 PART 2	**Comply**
EU POPs ((EU) 2019/1021) & UK POPs	**Comply**
China RoHS (Decree No. 32 of the Chinese Ministry of Industry and Information Technology)	**Comply**

Approved by Senior Engineer:	2025-10-17	Huang Xuan	Huang Xuan
	Date	Name	Signature
Prepared by:	2025-10-17	Zhang Yaling	Zhang Yaling
	Date	Name	Signature

Modification Record

No.	Last Report No.	Modification Description
1	N/A	First report

Remark: This report is evaluated based on the documents and declarations of material environmental compliance provided by the applicant.

List of abbreviations

No.	Abbreviations	Full spelling
1	RoHS	the Restriction of the use of certain hazardous substances in electrical and electronic equipment
2	REACH	Regulation concerning the Registration, Evaluation, Authorisation and Restriction of Chemicals
3	SVHC	Substances of Very High Concern
4	WEEE	Waste Electrical and Electronic Equipment
5	MCD	Material Composition Declaration
6	BOM	Bill of Materials
7	PDM	Product Data Management
8	Insight	Product Compliance Management Platform
9	ppm	parts per million
10	NA	Not Applicable
11	3R	Recovery, Reuse and Recycling

Contents

1 General Information

1.1 Applied Standards

Applied Regulations & Standards	:	• Directive 2011/65/EU & (EU) 2015/863 (EU RoHS) • The Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment Regulations 2012 (UK RoHS) • IEC 63000:2016&EN IEC 63000: 2018 & BS EN IEC 63000: 2018 • Regulation (EC) No 1907/2006 (REACH) • Directive 94/62/EC (Packaging and Packaging Waste) Article 11&Regulation (EU) 2025/40(Packaging and Packaging Waste Regulation, PPWR) Article 5.4 • The Packaging (Essential Requirements) Regulations 2015 (UK Packaging Regulations) • Regulation (EU) 2019/1021 (EU POPs) • The Persistent Organic Pollutants Regulations 2007 (UK POPs) • Directive 2012/19/EU (EU WEEE) ANNEX V • The Waste Electrical and Electronic Equipment Regulations 2013 (UK WEEE) SCHEDULE 11 PART 2 • China RoHS (Decree No. 32 of the Chinese Ministry of Industry and Information Technology) GB/T 36560-2018 Specifications for technical documentation for the conformity demonstration of electrical and electronic products with respect to the restriction of hazardous substances SJ/T 11364:2024 Requirements on the Marking for the Restriction of Hazardous Substances in Electrical and Electronic Products
Test Methods	:	See details in the report

1.2 Company to perform the evaluation

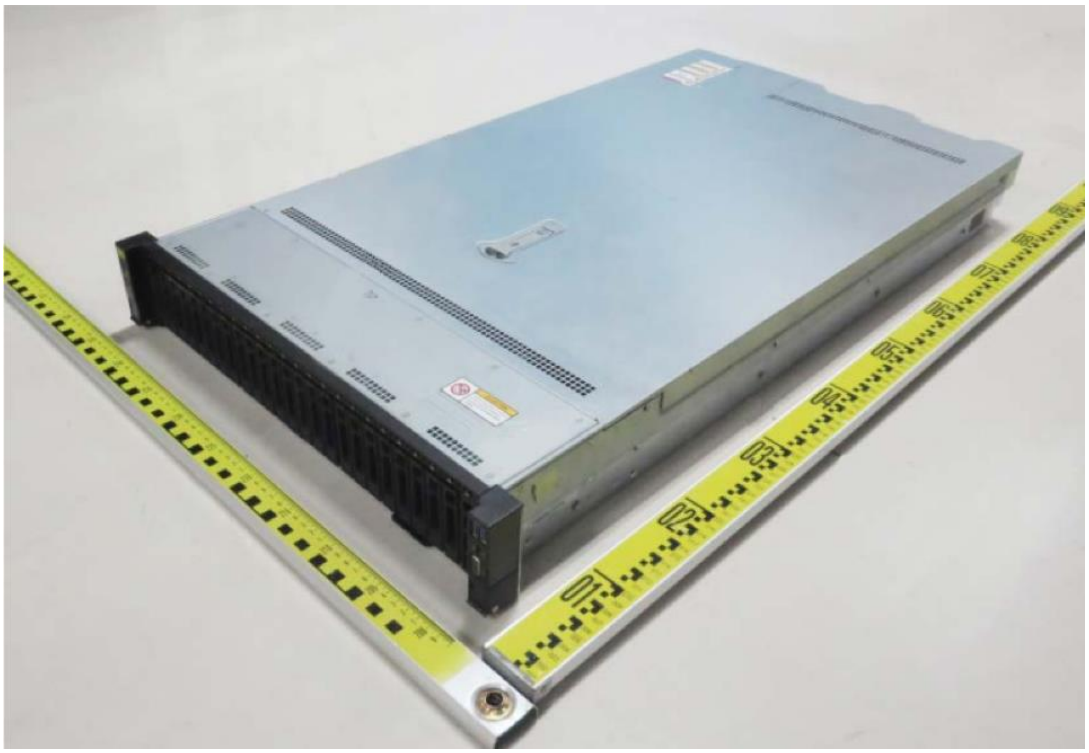
Company name	:	Reliability Laboratory of xFusion Digital Technologies Co., Ltd.
Company Address	:	Block A, Bojin International (Bojin Business Plaza), No. 1 Tairan 7th Road, Chegongmiao, Futian District, Shenzhen, P.R.C

2 Product Description

2.1 General description

FusionServer 2288 V8 (hereinafter referred to as 2288 V8) is a new generation 2U 2-socket rack server based on the Intel® Xeon® 6 Processors of 6500P/6700P/6700E-series designed for the Internet, Internet Data Center (IDC), cloud computing, enterprise, and telecom.
This product is ideal for IT core services, cloud computing, virtualization, high-performance computing, distributed storage, big data processing, enterprise or telecom applications, and other complex workloads. This product features low power consumption, high scalability, high reliability, and easy management and deployment.

2.2 Product photos



3 Review of the Documents of Conformity

According to IEC 63000:2016, EN IEC 63000: 2018 and BS EN IEC 63000: 2018, the manufacturer shall collect supplier declarations and/or contractual agreements, and/or material declarations and/or analytical test results for materials, parts, and/or sub-assemblies from all suppliers. As per xFusion's requirements, all suppliers shall sign the supplier declarations (*Quality and Environment Assurance Agreement* and *Indemnity Agreement for Quality and Environment Problems of Supplier's Materials* and/or *Declaration of Non-use of Restricted Substances* which declares that suppliers' products meet the requirement of EU RoHS, REACH, packaging directive, POPs and Proposition 65 of California) and provide the MCDs (Material Composition Declaration) to prove that their products comply with all of above requirements. Additionally, the analytical test reports of high risk materials (identified by the manufacturer) shall be provided.

Based on the evaluation of quality and trustworthiness of these documents, xFusion decides that the documents provide sufficient evidence of compliance and shall be included in the technical documentation.

Remark: The battery, which is integrated in the server and covered by Regulation（EU）2023/1542, is produced by other manufacturers, so this report doesn't cover the evaluaiton of the battery. xFusion will require the battery manufacture to strictly follow the requirements of Regulation（EU）2023/1542.

4 The Evaluation of RoHS Compliance

4.1 The Evaluation of Materials/Samples

According to EN IEC 63000: 2018 and BS EN IEC 63000: 2018, the related documents (supplier declarations and MCDs) are collected from the suppliers of the materials, parts and sub-assemblies (see chapter 3 of this report), and high-risk materials identified are tested by the suppliers. The qualified procedure is established to evaluate all of these documents collected. As per the Directive 2011/65/EU and amendments, and UK RoHS, the evaluation results are summarized in Table 3.

4.2 The Test of High Risk Material/Samples

The high risk materials tested are listed below:

(1) High Risk Materials/Samples Information

Table 1 Evaluation results of high risk materials / samples for RoHS

Item	Evaluation of High Risk Materials / Samples		
High Risk Material Information	Amount		
	High Risk Samples in Product [1]	Tested Samples	Failed Samples
	97	97	0
Result [2]	**Comply**		

Remark:

1. As per xFusion's "Guide to Grading RoHS Compliance Risk Levels of Materials", and "Annex D in GB/T26572", the high risk materials include solder (Pb), plating layer (Pb, Cr(VI)), plastic colorant (Pb, Cd and Cr(VI)), ABS (Acrylonitrile Butadiene Styrene) plastic (PBDE), PVC (Polyvinyl Chloride) plastic (Pb, Cd), PP (Polypropylene) plastic (PBDE), PET (Polyester Terephthalate) plastic (PBDE), PBT (Polybutylene Terephthalate) plastic (PBDE), coatings (Pb), cable jacketing and other soft plastics (phthalate substances DEHP, BBP, DBP and DIBP) and alloy (Pb, Cd and Cr(VI)).
2. The results are based on the evaluation results and the exemptions in EU RoHS & UK RoHS, and all exemptions applied to the evaluated product materials are taken as "Pass" for the evaluation results.

(2) Test Items and Methods of the High Risk Materials

As per the information provided by the suppliers, the high risk materials are tested with the following methods.

Table 2 Test Methods of High Risk Materials for RoHS

Test Items	Test Methods
Cadmium (Cd)	With reference to EN/IEC 62321-5, by acid digestion and determined by ICP-OES
Lead (Pb)	
Mercury (Hg)	With reference to EN/IEC 62321-4, by acid digestion and determined by ICP-OES
Hexavalent chromium [Cr(VI)]	With reference to EN/IEC 62321-7-1& EN/IEC 62321-7-2 by solvent extraction and determined by UV-VIS
Polybrominated biphenyls (PBB)	With reference to EN/IEC 62321-6, by solvent extraction and determined by GC/MS
Polybrominated diphenyl ethers (PBDE)	
Bis(2-ethylhexyl) phthalate (DEHP)	With reference to EN/IEC 62321-8, by solvent extraction and determined by GC/MS
Butyl benzyl phthalate (BBP)	
Dibutyl phthalate (DBP)	
Diisobutyl phthalate (DIBP)	

4.3 Evaluation Results

The limits of restricted substances are quoted from EU RoHS and UK RoHS for homogeneous material and the results are shown in Table 3.

Table 3 Evaluation Results against RoHS Restricted Substances Limits

Restricted Substances	Limits	Results in material/sample
Cadmium (Cd)	0.01% (100 ppm)	PASS
Lead (Pb)	0.1% (1000 ppm)	PASS
Mercury (Hg)	0.1% (1000 ppm)	PASS
Hexavalent chromium [Cr(VI)]	0.1% (1000 ppm)	PASS
Polybrominated Biphenyls (PBB)	0.1% (1000 ppm)	PASS
Polybrominated Diphenyl Ethers (PBDE)	0.1% (1000 ppm)	PASS
Bis(2-ethylhexyl) phthalate (DEHP)	0.1% (1000 ppm)	PASS
Butyl benzyl phthalate (BBP)	0.1% (1000 ppm)	PASS
Dibutyl phthalate (DBP)	0.1% (1000 ppm)	PASS
Diisobutyl phthalate (DIBP)	0.1% (1000 ppm)	PASS

Remark: The evaluation results are based on the full configuration of the product (See Annex Ⅱ).

5 The Evaluation of REACH Compliance

5.1 The Evaluation of REACH SVHC

Based on the documents collected from the suppliers of material, parts and sub-assemblies (see chapter 3 of this report), the evaluation against the substances in the most updated *Candidate List of Substances of Very High Concern (SVHC) for authorization published by European Chemicals Agency (ECHA)* regarding Regulation (EC) No 1907/2006 concerning the REACH is performed. The SVHC in a concentration above 0.1% (w/w) of “article” in the product (including batteries and packaging materials) identified are listed as below.

Table 4 SVHC in a concentration above 0.1% weight by weight

SVHC in a concentration above 0.1% weight by weight	CAS No.
1,3,5-TRIS(OXIRAN-2-YLMETHYL)-1,3,5-TRIAZINANE-2,4,6-TRIONE (TGIC)	2451-62-9
OCTAMETHYLCYCLOTETRASILOXANE	556-67-2
2,2',6,6'-TETRABROMO-4,4'-ISOPROPYLIDENEDIPHENOL(TBBP-A)	79-94-7
BIS(2-ETHYLHEXYL) TETRABROMOPHTHALATE COVERING ANY OF THE INDIVIDUAL ISOMERS AND/OR COMBINATIONS THEREOF	-
DIARSENIC TRIOXIDE	1327-53-3
1, 2-DIMETHOXYETHANE; ETHYLENE GLYCOL DIMETHYL ETHER (EGDME)	110-71-4
N,N-DIMETHYLACETAMIDE	127-19-5
4,4'-ISOPROPYLIDENEDIPHENOL BISPHENOL A	80-05-7
DIPHENYL(2,4,6-TRIMETHYLBENZOYL) PHOSPHINE OXIDE	75980-60-8
2-(DIMETHYLAMINO)-2-[(4-METHYLPHENYL)METHYL]-1-[4-(MORPHOLIN-4-YL)PHENYL]BUTAN-1-ONE	119344-86-4
TRIPHENYL PHOSPHATE	115-86-6
LEAD	7439-92-1

Remark:

1. Article 33 of (EC) No. 1907/2006 requires supplier of an article containing SVHC in a concentration above 0.1% weight by weight shall provide the recipient of the article with sufficient information, available to the supplier, to allow safe use of the article including, as a minimum, the name of that SVHC.
2. “Article” in product means an object which during production is given a special shape, surface or design which determines its function to a greater degree than does its chemical composition (according to Regulation (EC) No 1907/2006). The limit of 0.1% (w/w) applies to every article in the product. The results are calculated based on an article defined by decision C-106/14 of EuGH of 10th September 2015.
3. In accordance with Regulation (EC) No 1907/2006, any EU producer or importer of articles shall notify ECHA, in accordance with paragraph 4 of article 7,if a substance meets the criteria in Article 57 and is identified in accordance with Article 59(1) of the regulation, if (a) the substance in the Candidate List is present in those articles in quantities totaling over one tonne per producer or importer per year; and (b) the substance in Candidate List is present in those articles above a concentration of 0.1% weight by weight（W/W）.
4. The evaluation results are based on the full configuration of the product (See Annex Ⅱ).

In conclusion, after the evaluation, 12 SVHCs in a concentration above 0.1% weight by weight are identified and listed in above Table 4.

5.2 The Evaluation against Annex XVII to REACH

Based on the documents collected from the suppliers of material, parts and sub-assemblies (see chapter 3), the restricted substances listed in Annex XVII (if applicable) to REACH Regulation are evaluated. The evaluation results are described in the Table below.

Table 5 The Evaluation Results against Annex XVII to REACH (if applicable)

Material Descriptions	Restricted Substances	Requirements	Results in material/sample
All Materials	Monomethyl – tetrachlorodiphenylmethane (Ugilec 141)	Prohibited	PASS
All Materials	Monomethyl-dichloro-diphenyl methane (Ugilec 121, Ugilec 21)	Prohibited	PASS
All Materials	Monomethyl - dibromo - diphenylmethane, bromobenzyl toluene (DBBT)	Prohibited	PASS
All Materials	Dimethyl fumarate (DMF)	0.1ppm	PASS
All Materials	Asbestos fiber	Prohibited	PASS
All Materials	Organotin compounds	total content < 1000 ppm	PASS
All Materials	Benzene	Prohibited	PASS
All Materials	Polychlorinated terphenyls and their derivatives (PCTs)	50ppm	PASS
Dye or colorant for plastics, textiles, leather products	Azo dyes	30ppm	PASS
Direct and long contact with the skin of the electroplating, corrosion-resistant alloy materials	Nickel and its compounds	0.5 μg/cm^2/ week	PASS
textiles, leather products	Nonylphenol (NP) Nonylphenol polyoxyethylene ether (NPEO)	100ppm	NA
textiles	Tris (2,3-dibromopropyl) phosphate (TRIS)	Shall not be used	NA
textiles	Tri- (aziridinyl) phosphine oxide (TEPA)	Shall not be used	NA
Wooden packaging material	Arsenic and its compounds	Shall not be used	PASS
Wooden packaging material	Creosote, naphthalene oil, anthracene oil, tar acid, alkaline low temperature tar etc.	Shall not be used	PASS

Rubber or plastic material on the exterior or user contact surface of the product	Polycyclic Aromatic Hydrocarbons (PAHs)	Single PAHs substance (BaP;BeP;BaA;BbFA;BjFA;BkFA;CHR;DBAhA;Benzo[g,h,i]perylene;Indeno[1,2,3-cd]pyrene) < 1ppm	PASS
Thermal paper	Bisphenol A	200ppm	NA
All materials	Phenylmercury	100ppm(the concentration of mercury)	PASS

Remark: The evaluation results are based on the full configuration of the product (See Annex Ⅱ).

In conclusion, as per the results shown in Table 5, the results of restricted substances in submitted sample comply with the requirements of Annex XVII to REACH (if applicable).

6 The Evaluation against Restricted Substances Requirements in Packaging Directive

Based on the documents collected from the suppliers of the packages (see chapter 3), the restricted substances regulated in 94/62/EC (Packaging and Packaging Waste) Article 11 &Regulation (EU) 2025/40 (Packaging and Packaging Waste Regulation, PPWR) Article 5.4 and UK Packaging Regulations (The Packaging (Essential Requirements) Regulations 2015) are evaluated. The evaluation results are listed in Table 6.

Table 6 The Evaluation Results against Restricted Substance Requirements in the Packaging Regulations

Material Descriptions	**Report No.**	**Requirements in Directive 94/62/EC Article 11&Regulation (EU) 2025/40 Article 5.4& UK Packaging Regulations**	**Results of Restricted Substances (ppm)**				
			Cd	**Pb**	**Hg**	**Cr(VI)**	**Sum**
All materials in the packages	-	The sum of Cd, Pb, Hg and Cr(VI) < 100 ppm	PASS	PASS	PASS	PASS	<100
Conclusion		**Comply**					

The evaluation of SVHC contained in the packaging materials are specified in chapter 5.1.

7 The Evaluation of POPs Compliance

According to EU POPs Regulation (EU) 2019/1021 & UK POPs Regulation (The Persistent Organic Pollutants Regulations 2007), the manufacturing, placing on the market and use of substances listed in Annex I & Annex II, whether on their own, in mixtures or in articles, shall be prohibited. Unless it complies with the following conditions:

(a) a substance used for laboratory-scale research or as a reference standard;
(b) a substance presented as an unintentional trace contaminant, as specified in the relevant entries of Annex I or II, in substances, mixtures or articles.

Based on the documents collected from the suppliers of the materials, parts and sub-assemblies (see chapter 3), the prohibited substances listed in (EU) 2019/1021 and UK POPs Regulation specified in the paragraph 1 of this chapter, if applicable, are evaluated. The evaluation results are described in Table 7.

Table 7 Evaluation Results against prohibited substances of POPs Regulation (if applicable)

Material Descriptions	Prohibited Substances	Limit	Results in material / sample
All Materials	Tetrabromodiphenyl ether, Pentabromodiphenyl ether, Hexabromodiphenyl ether, Heptabromodiphenyl ether, Decabromodiphenyl ether	1000ppm (follow the limits defined in RoHS Directive)	PASS
All Materials	Perfluroctane sulfonic acid (PFOS) and its salts	25ppb	PASS
	Perfluroctane sulfonic acid (PFOS) related compounds	1ppm	PASS
All Materials	Hexachlorobenzene	Shall not be used	PASS
All Materials	Pentachlorobenzene	Shall not be used	PASS
All Materials	Polychlorinated Biphenyls (PCB)	Shall not be used	PASS
All Materials	Hexabromobiphenyl	Shall not be used	PASS
All Materials	Hexabromocyclododecane	100ppm	PASS
All Materials	Hexachlorobutadiene	Shall not be used	PASS
All Materials	Pentachlorophenol and its salts and esters	5ppm	PASS
All Materials	Polychlorinated naphthalenes(PCNs)	Shall not be used	PASS
All Materials	Alkanes C10-C13, chloro (short-chain chlorinated paraffins) (SCCPs)	1500ppm	PASS
All Materials	Perfluorooctanoic acid (PFOA) and its salts	25ppb	PASS
	Perfluorooctanoic acid (PFOA) related substances	1ppm	PASS
All Materials	Perfluorohexane sulfonic acid (PFHxS) and its salts	25ppb	PASS
	Perfluorohexane sulfonic acid (PFHxS) related compounds	1ppm	
All Materials	2-(2H-benzotriazol2-yl)-4,6-di-tert-pentylphenol (UV-328)	100ppm	PASS
All Materials	Dechlorane Plus	1000ppm	PASS
Packaging Materials, Transport Materials	DDT (1,1,1-trichloro-2,2-bis(4-chlorophenyl)ethane),Chlordane ,	Shall not be used	PASS

	Hexachlorocyclohexanes including lindane, Dieldrin, Endrin, Heptachlor, Endosulfan, Chlordecone, Aldrin, Mirex, Toxaphene, Dicofol,Methoxychlor		

Remark: The evaluation results are based on the full configuration of the product (See Annex Ⅱ).

In conclusion, as per the results shown in Table 7, the results of prohibited substances in submitted sample comply with the requirements of Annex I to EU POPs Regulation and UK corresponding regulation.

8 WEEE 3R (Recovery, Recycling & Reuse) Evaluation

8.1 WEEE 3R Results

According to the evaluation process of WEEE 3R described in chapter 9.2, the below result can be gotten in below Table:

Table 8 Conclusion of WEEE 3R for Evaluated Product

Product Name	Server	
Product Category	Large equipment excluding photovoltaic panels	
Reuse/recycling/recovery (3R)	Recovery (%)	Reuse & Recycling (%)
Evaluation Result	95.30%	90.10%
3R Requirements in WEEE for the Product	85%	80%
3R Compliance for the Product	**Comply**	**Comply**

8.2 WEEE 3R Calculation

As per xFusion's evaluation instructions of WEEE 3R and IEC TR 62635-62650, referencing the actual 3R data of EEE products, we analysis the materials/parts information incorporated in the Insight system. Finally, the results of 3R of this Server are listed in Table 9:

Table 9 Results of WEEE 3R for Evaluated Product

Material / Part Description	Weight Ratio (%)	Recoverability Rate (%)	Reuse and Recyclability Rate (%)	Weight Ratio of Recovery (%)	Weight Ratio of Reuse & Recycling (%)
(1) Parts required selective treatment					
Power Cable	4.95%	90%	85%	4.46%	4.21%
Capacitor (PCB/PCT)	0.00%	90%	85%	0.00%	0.00%
PCB (Printed Circuit Board)	24.74%	90%	70%	22.27%	17.32%
BFR* Plastics	0.00%	90%	0%	0.00%	0.00%
Electrolyte Capacitors	0.00%	0%	0%	0.00%	0.00%
(2) Parts difficult to process					
Compressors	0.00%	90%	90%	0.00%	0.00%
AC Motor	0.00%	90%	90%	0.00%	0.00%
Resin Motor	0.00%	0%	0%	0.00%	0.00%
Transformer	0.00%	90%	90%	0.00%	0.00%

(MWO)					
(3) Parts which go to separation process					
ABS (Acrylonitrile Butadiene Styrene)	1.44%	90%	90%	1.30%	1.30%
PC (Polycarbonate)	1.80%	90%	90%	1.62%	1.62%
PET (Polyethylene Terephthalate)	0.00%	90%	90%	0.00%	0.00%
PP (Polypropylene)	0.00%	90%	90%	0.00%	0.00%
PS (Polystyrene)	0.00%	90%	90%	0.00%	0.00%
PBT (Polybutylene terephthalate)	0.00%	90%	90%	0.00%	0.00%
PVC (Polyvinyl chloride)	0.00%	90%	0%	0.00%	0.00%
POM (Polyoxymethylene)	0.00%	90%	90%	0.00%	0.00%
EP (Epoxy Resin)	0.00%	90%	0%	0.00%	0.00%
Steel	55.60%	98%	98%	54.49%	54.49%
Aluminum	6.75%	98%	98%	6.62%	6.62%
Copper	2.25%	98%	98%	2.21%	2.21%
Zinc	2.25%	98%	98%	2.21%	2.21%
Rubber	0.00%	90%	0%	0.00%	0.00%
Fiberglass	0.00%	80%	80%	0.00%	0.00%
Others	0.22%	60%	60%	0.13%	0.13%
Total	**100.00%**	**-**	**-**	95.30%	90.10%

Remark：

1. Abbreviations are listed as below:

   3R = Recovery, Reuse and Recycling

   WEEE = Waste Electrical and Electronic Equipment

   BFR* = Brominated Flame Retardants

2. The evaluation results are based on the typical configuration of the product (See Annex Ⅲ).

3. According to EU WEEE& UK WEEE, Reuse, Recycling & Recovery Rate using in the report are calculated as following formulas.

$$\text{Recovery Rate (\%)} = \frac{Reuse\ \&Recycling\ Weight + Energy\ Recovery\ Weight}{Product\ Tatal\ Weight} \times 100\%$$

$$\text{Reuse \& Recycling Rate (\%)} = \frac{Reuse\ \&\ Recycling\ Weight}{Product\ Tatal\ Weight} \times 100\%$$

8.3 Preparation for Recovery, Recycling and Reuse of the Product

According to Articles 8 and the Annex VII of Directive 2012/19/EU (WEEE Directive), the following substances, mixtures and components listed in Table 10 have to be removed and be selectively treated when during the evaluation.

Table 10 Removed Components in the Product

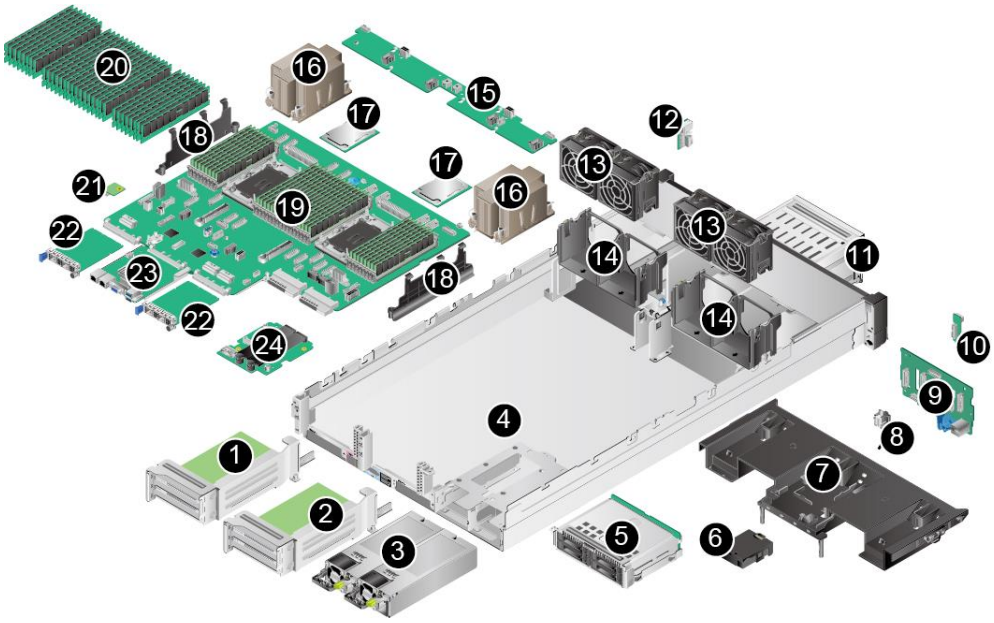
Descriptions of Parts and Materials	Remarks	Quantity
Capacitors / condensers (Containing PCB/PCT)	Polychlorinated biphenyls and polychlorinated terphenyls (PCB/PCT)	0
Mercury-containing components	Such as mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Printed Circuit Boards (PCB) or Printed Circuit Board Assemblies (PCBA)	Printed circuit boards of mobile phones generally, and of other devices if the surface of the printed circuit board is greater than 10 square centimeters	10
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations	0
Plastics containing Brominated Flame Retardants	Brominated Flame Retardants include PBB, PBDE, HBCDD and so on	0
Components and waste containing asbestos	-	0
Cathode Ray Tubes (CRT)	-	0
Chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)	-	0
Gas Discharge Lamps	-	0
Liquid Crystal Displays (LCD)	With a surface greater than 100 sq cm, includes background illuminated displays with gas discharge lamps	0
External electrical cables and cords	-	2
Components, parts and materials containing refractory ceramic fibres	Described in Commission Directive 97/69/EC adapting to technical progress Council Directive 67/548/EEC relating to the classification, packaging and labeling of dangerous substances (2)	0
Components, parts and materials containing radioactive substances	With the exception of components that are below the exemption thresholds set in Article 3 of an Annex I to Council Directive 96/29/Euratom laying down basic safety standards for the protection of the health of workers and the general public against the dangers arising from ionizing radiation (3)	0

Electrolyte capacitors containing substances of concern	Height > 25 mm, diameter > 25 mm or proportionately similar volume	0

8.4 Sketch Figure of Sample Disassembly

The disassembly procedure taken here is in accordance with the treatment requirements under EU WEEE & UK WEEE, and based on economic and efficiency factor, disassembly tools, and current state of the art of recycling and recovery technology. The detailed information for sample disassembly can be described as below in Figure 1.

Figure 1 Sketch Figure of Evaluated Sample Disassembly



1	Rear I/O module 1	2	Rear I/O module 2
3	PSU	4	Chassis
5	Rear I/O module 3	6	Supercapacitor
7	Air duct	8	Intrusion sensor
9	Front-Drive Backplane	10	Left mounting ear plate
11	Front-drive module	12	Right mounting ear plate
13	Fan module	14	Fan module bracket
15	Fan Board	16	Processor heat sink
17	Processor	18	Cable management arm
19	Mainboard	20	DIMM
21	TPM	22	OCP 3.0 NIC
23	BMC card	24	M.2 SSD

Annex I China RoHS Hazardous Substances Information Evaluation

According to China RoHS (the Administrative Measures for the Restriction of the Use of Hazardous Substances in Electrical and Electronic Products, Decree No. 32 of the Chinese Ministry of Industry and Information Technology), the producers and importers of electrical and electronic products shall mark the name, content, and locations of hazardous substance of the products within the market.

In accordance with the Requirements on the Marking for the Restriction of Hazardous Substances in Electrical and Electronic Products (SJ/T 11364) , referring to GB/T 26572 and it's Amendment No. 1 , the assessment results of hazardous substance content in components are shown in the table below:

Table I.1 Names and Content of Hazardous Substances

Component		PCBA	Cables	Metal parts
Hazardous Substances	**Pb**	×	×	×
	Hg	○	○	○
	Cd	○	○	○
	Cr(VI)	○	○	○
	PBBs	○	○	○
	PBDEs	○	○	○
	DBP	○	○	○
	DIBP	○	○	○
	BBP	○	○	○
	DEHP	○	○	○

Note 1:

-O: Indicate that the content of the hazardous substance contained in all of the homogenous materials in the component is within the limits of the national standard for hazardous substances in electric and electronic products.

-×: Indicate that the content of the hazardous substance contained in at least one homogenous material exceeds the limits of the national standard for hazardous substances in electric and electronic products.

Note 2:

For components not listed above, their hazardous substance content is within the limits of national standard of hazardous substances in electrical and electronic products.

Annex Ⅱ Full Configuration of Product

Board list		
Board Name	Description	Qty.
BC16MBSC	ManufacturedBoard,BC16MBSC,1288 V8/2288 V8 Server motherboard,1*1	1
BC16HBBD	Manufactured Board,2288 V8,BC16HBBD,8*2.5inch SAS/ SATA 3Cage Disk Backplane,1*2	3
BC16NHBC	Manufactured Board,2288 V8,BC16NHBC,8*2.5inch SAS/SATA/NVMe 3Cage Disk Backplane,1*2	3
BC16NHBD	Manufactured Board,2288 V8,BC16NHBD,12*3.5inch (8*SAS/SATA+4*SAS/SATA/NVMe)Disk Backplate,1*2	1
BC15HBBA	Manufactured Board,2288H V7,BC15HBBA,8*2.5" SAS/ SATA HDD backplane,1*2	1
BC15HBBE	Manufactured Board,2288H V7,BC15HBBE,IO1/ IO2 2*2.5" SAS/SATA HDD backplane,2*2	2
BC15HBBF	Manufactured Board,2288H V7,BC15HBBF,IO1/ IO2 2*3.5" SAS/SATA HDD backplane,2*4	2
BC15HBBI	Manufactured Board,2288H V7,BC15HBBI,IO3 4*SAS/SATA/ NVMe HDD backplane,1*4	1
BC15HBBS	Manufactured Board,2258 V7,BC15HBBS, IO3 4*NVMe HDD backplane,1*4	1
BC15NHBS	Manufactured Board,2258 V7,BC15NHBS,8 * 2.5-inch SAS/ SATA/NVMe Hard RAID HDD backplane,1*2	3
BC26SMMAA	Manufactured Board, BC26SMMAA, DC-SCM Hi1711 BMC Card,2*1	1
BC15MSMA	Manufactured Board,2288H V7,BC15MSMA,inner M.2 adapter, support PCH SATA/PCIe,2*1	1
BC26HBMA	Manufactured Board,2158H V8,BC26HBMA,BC26HBMA,1*1	1
BC16HBMA	Manufactured Board,BC16HBMA, 16Port Cable SATA Controller Card,2*2	1
BC16HBMAA	Manufactured Board,BC16HBMAA, 8Port Cable SATA Controller Card,2*2	1
BC15RCIA	Manufactured Board,2288H V7,BC15RCIA, Right Customer Interface Board,1*1	1
BC82LCIA	Manufactured Board,TaiShan 2280 V2,BC82LCIA, Left Customer Interface,4*2	1
BC15FDCA	Manufactured Board,2288H V7,BC15FDCA, Fan Board 4*8080+/8038+,1*3	1
BC16MBSCA	Manufactured Board,BC16MBSCA,Server board,1*1	1

BC16EHBA	Manufactured Board,2288 V8, BC16EHBAA,14*E3. S-1T NVMe 3Cage Disk Backplate,1*2	3
BC15NHBZ	Manufactured Board,BC15NHBZ,8*2.5" SAS/SATA/ NVMe HDD backplane,1*3	1
BC19NHBC	Manufactured Board,BC19NHBC,IO3 4*2.5" SAS/SATA/ NVME Horizontal Backplane Board1,1*1	2
BC19NHBD	BC19NHBD,IO3 4*2.5" SAS/SATA/ NVME Horizontal Backplane Board 2,2*2	2
BC19NHBC	PCB,BC19NHBC,IO3 4*2.5" SAS/SATA/ NVME Horizontal Backplane Board1,2*2	1
BC16NHBH	Manufactured Board,BC16NHBH,4*2.5inch SAS/SATA/NVMe 3Cage NVMe RAID Disk Backplate,1*1	1
BC15HBBG	SATA/NVMe 3Cage NVMe RAID Disk Backplate, 1*1 SATA HDD backplane,1*4	1
BC15HBEC	Manufactured Board,2288H V7,BC15HBEC, 12*3.5inch HDD Expander Backplane Board,1*2	1
BC15HBED	Manufactured Board,2288H V7,BC15HBED, 25*2.5inch HDD Expander Backplane Board,1*2	1
BC15NHBR	Manufactured Board,2258 V7,BC15NHBR, 12*3.5" SAS/SATA/NVMe HDD backplane,1*2	1
BC26HBBA	Manufactured Board,2158H V8,BC26HBBA, 8*3.5" SAS/SATA/NVME HDD Backplane Board,1*2	1
BC16SMMD	Manufactured Board,BC16SMMD,Hi1711 BMC Card,1*1	1
BC26FDTA	Manufactured Board,2158H V8,BC26FDTA, AMD Server 2U1P Fan Board 6*6056,1*2	1
BC16CNTD	Manufactured Board,BC16CNTD, Fornt IO BMC MGNT Port Connector Board,1*1	1
BC16PDBA	Manufactured Board,BC16PDBA,2*2	2

Subassembly list	
Subassembly Name	Description
Plastic parts	Plastic,2120Y422_DRAEN.ASM,Air duct(2U radiator),2288V8
Plastic parts	Plastic,2120Y447_DRAEN.ASM,Air duct(1U radiator),2288 V8
BMC Card	Manufactured Board,BC16SMMD,Hi1711 BMC Card,1*1
BMC Card	Manufactured Board,BC26SMMAA,DC-SCM Hi1711 BMC Card,1*1
FAN	Fan Assembly,10.8V,13.2V,80*80*38,80mm,8,54W,105CFM
FAN	Fan Assembly,10.8V,13.2V,80*80*56,80mm,8PIn,120W,130CFM
Riser Card	Manufactured Board,BC16PRUJ,IO1 Riser1 butterfly Riser- 2*x16(2*PCIe5.0x16),1*6
Riser Card	Manufactured Board,BC16PRUF,IO2 Riser1-1*CEM(Slot3),1*4
Riser Card	Manufactured Board,BC16PRUH,Front IO1/IO2 Riser1-2*CEM(Slot52/53),1*1

Riser Card	Manufactured Board,BC16PRUK,IO1/IO2 Riser1-2*x16 (2*PCIe5.0x8)(Slot2/3)+1CEM(Slot1),1*2
Riser Card	Manufactured Board,BC16PRUKA,IO1/IO2 Riser6-2*x16 (2*PCIe5.0x8)(Slot2/3),1*1
Riser Card	Manufactured Board,BC16PRUN,IO1/IO2 Riser1-2*x16 (2*PCIe4.0x8)(Slot2/3)+1CEM(Slot1),1*2
Riser Card	Manufactured Board,BC16PRUL,IO1/IO2 Riser2-1*x16 (1*PCIe5.0x16)(Slot3)+2CEM(Slot1/2),1*1
Riser Card	Manufactured Board,BC16PRUD,IO1/IO2 Riser3-1*x16 (1*PCIe5.0x16)(Slot3),1*1
Riser Card	Manufactured Board,BC16PRUE,IO3 Riser1-2CEM(Slot7/8),1*1
Riser Card	Manufactured Board,BC16PRUEA,IO3 Riser2-1*CEM(1*PCIe5.0x16)(Slot2),1*1
Riser Card	Manufactured Board,BC16PRUI,IO1/IO2 Riser4-1*x16 (1*PCIe5.0x16) (Slot2)+1CEM(Slot1),1*1
Riser Card	Manufactured Board,BC16PRVA,IO1/IO2 DPU Riser1-2*x16(2*PCIe5.0x16) (Slot2/3)-Slot2 supports double width DPU,1*1
Riser Card	Manufactured Board,BC16PRUEB,Riser-2*CEM-MCIO x16,1*1
Riser Card	Manufactured Board,BC16PRVB,IO1/IO2 DPU Riser2-1*x16 (1*PCIe5.0x16)(Slot3)-Slot3 supports single width DPU,1*1
Riser Card	Manufactured Board,BC16PRUG,Front IO1/ IO3 Riser1-4*CEM(Slot50/51/52/53),1*1
Riser Card	2288 V8-BC19PRUG Front IO1/IO3 Riser1-4*CEM (Slot50/51/52/53) Board Assembled
Riser Card	2288 V8-BC16PRUIA-IO1/IO2 Riser - 1 x 16 (1 x PCIe 5.0 x 16) (Slot 2)
Riser Card	2288 V8-BC16PRULA-IO1 Riser - 1 x 16 (1 x PCIe 5.0 x 16) (Slot 3) + 2 x CEM (2 x PCIe 5.0 x 16) (Slot 1/2)
Riser Card	2288 V8-BC16PRULB-IO2 Riser - 1 x 16 (1 x PCIe 5.0 x 16) (Slot 3) + 2 x CEM(2 x PCIe 5.0 x 16) (Slot 1/2)
PSU Adapter Board	Manufactured Board,BC16CNTG,PSU Gold Finger Adapter Board,2*2
RAID CARD	Manufactured Board-JDM,Public Module,BC55RLAD,XC470C-M-8i 4G-(SAS3908)-RAID Cable Card-RAID0,1,5,6,10,50,60-12Gb/s-4GB Cache, Capacitor and Management,PCIE 4.0 X8-Vendor ID 1000-Device ID 10E2-1-Subvendor ID 1F24-Subdevice ID 3000,1*1
RAID CARD	Other Cards,PCIE 4.0 X8-Vendor ID 1000-Device ID 10E2-1-Subvendor ID 1000-Subdevice ID 4010-12G SAS RAID card,x8 PCIe 4.0-9560-8i SAS RAID Card,SAS3908,4G CacheVault,CVPM05-12Gb/s SAS,6Gb/s SATA,PCIe(NVMe),9560-8i
RAID CARD	Manufactured Board-JDM,Public Module,BC55RLADB,XC470C-M-16i 4G-(SAS3916)-RAID Cable Card-RAID0,1,5,6,10,50,60-12Gb/s-4GB Cache, Capacitor and Management,PCIE 4.0 X8-Vendor ID 1000-Device ID 10E2-1-Subvendor ID 1F24-Subdevice ID 3001,1*1

RAID CARD	Other Cards,PCIE 4.0 X8-Vendor ID 1000-Device ID 10E2-1-Subvendor ID 1000-Subdevice ID 4000-12G SAS RAID card,x8 PCIe 4.0-9560-16i SAS RAID Card,SAS3916,8G CacheVault,CVPM05-12Gb/s SAS, 6Gb/s SATA,PCIe(NVMe),9560-16i
RAID CARD	Other Cards,PCIE 4.0 X8-Vendor ID 1000-Device ID 10E6-1-Subvendor ID 1000-Subdevice ID 40D5-12G SAS RAID,x8 PCIe 4.0-9540-8i SAS RAID Card,SAS3808,No CacheVault,12Gb/s SAS,6Gb/s SATA,PCIe(NVMe), 9540-8i,Chinese doc,1pcs bracket
RAID CARD	Manufactured Board-JDM,Public Module,BC56RLAE,XC170-M-8i-(SAS3808iMR)-SAS/SATA RAID Cable Card-RAID0,1,10-12Gb/s-no Cache, Support Sideband Management,PCIE 4.0 X8-Vendor ID 1000-Device ID 10E6-1-Subvendor ID 1F24-Subdevice ID 3002,1*1
RAID CARD	Other Cards,PCIE 4.0 X8-Vendor ID 1000-Device ID 10E6-1-Subvendor ID 1000-Subdevice ID 40D0-12G SAS RAID,x8 PCIe 4.0-9540-16i SAS RAID Card,SAS3816,No CacheVault,12Gb/s SAS,6Gb/s SATA,PCIe(NVMe), 9540-16i,Chinese doc,1pcs bracket
RAID CARD	Manufactured Board,BC16HBMA,16Port Cable SATA Controller Card,2*2
RAID CARD	Manufactured Board,BC16HBMAA,8Port Cable SATA Controller Card,2*2
RAID CARD	Manufactured Board,Public Module,BC55RLAH1,XP270-M2-(SAS3808)-M.2 RAID PCIE card-RAID0,1,JBOD-No CacheSupport Sideband Management, PCIE 4.0 X8-Vendor ID 1000-Device ID 10E6-1-Subvendor ID 1F24-Subdevice ID 3002,1*2
RAID CARD	Other Cards,PCIE 4.0 X4-Vendor ID 1e3b-Device ID 50b1-1-Subvendor ID 1e3b-Subdevice ID 50b1,PCIE 4.0 X4-Dapustor F6100 RAID Card-DP808AL-6Gb/s SATA,PCIE5.0 X2 NVMe
RAID CARD	Manufactured Board,2158H V8,BC26HBMA, PCIe to SATA M.2 Backplane Board,1*1
RAID CARD	Manufactured Board,2288H V7,BC15MSMA,inner M.2 adapter, support PCH SATA/PCIe,2*1
RAID CARD	Other Cards,PCIE 4.0 X8-Vendor ID 1000-Device ID 10E6-1-Subvendor ID 1000-Subdevice ID 40E0-12G SAS RAID card,x8 PCIe 4.0-9540-2M2 SAS RAID Card,SAS3808,No CacheVault,12Gb/s SAS, 6Gb/s SATA,PCIe(NVMe),9540-2M2
PCIE Card	Network Card,200 Gigabit,64bit,QSFP56,2 ports,PCIE 5.0 x16-Vendor ID 14e4-Device ID 1760-2-Subvendor ID 14e4-Subdevice ID 9120
IB Card	IB Card,Infiniband MCX75310AAS-HEAT,200Gb/s NDR200 IB, single port OSFP,PCIE 5.0 x16-Vendor ID 15B3-Device ID 1021-1-Subvendor ID 15B3-Subdevice ID 0029,English doc,(IB&Ethernet)
IB Card	IB Card,Infiniband MCX755106AS-HEAT,2*200Gb/s NDR200 IB, Dual port QSFP112,PCIE 5.0 x16-Vendor ID 15B3-Device ID 1021-2-Subvendor ID 15B3-Subdevice ID 0022
IB Card	IB Card,Infiniband MCX75310AAS-NEAT,NDR/NDR200/HDR100/EDR IB single port OSFP-400Gb/s,PCIE 5.0 x16-Vendor ID 15B3-Device ID 1021-1-Subvendor ID 15B3-Subdevice ID 0023,English doc,(IB&Ethernet)

OCP Card	Manufactured Board-JDM,Public Module,BC53ETHF,XC310 GE350-T2 OCP3.0 Ethernet Card-2*GE(I350)-Dual Port-RJ45, PCIE 2.1 x4-Vendor ID 8086-Device ID 1521-2-Subvendor ID 1f24-Subdevice ID 200b,1*4
PCIE Card	Manufactured Board,Public Module,CN21ITGC1,XP212 I350 4*GE PCIE Card,PCIE 2.0 X4-Vendor ID 8086-Device ID 1521-4-Subvendor ID 1f24-Subdevice ID 2001,1*2
PCIE Card	Manufactured Board,Public Module,CN21ITGG1,XP330 Ethernet Adapter, 10Gb Optical Interface(Intel X710),2-Port,SFP+(without Optical Transceiver), PCIE 3.0 X8-Vendor ID 8086-Device ID 1572-2-Subvendor ID 1f24-Subdevice ID 2003,1*2
OCP Card	Manufactured Board-JDM,Public Module,BC53ETHH,XC331 OCP3.0 Ethernet Adapter-10GE(BCM57416)-Dual Port,RJ45-PCIE 3.0 X8-Vendor ID 14e4-Device ID 16d8-2-Subvendor ID 1f24-Subdevice ID 2010,1*3
PCIE Card	Network Card,25 GE,64bit,SFP28,2,PCIE 4.0 x8-15b3-101f-2,No Driver CD
OCP Card	Manufactured Board-JDM,Public Module,BC55ETHA,XC385 OCP3.0 Ethernet Adapter-25GE(CX6-Lx)-Dual Port-SFP28(without Optical Module)-PCIE 4.0 X8-Vendor ID 15b3-Device ID 101f-2-Subvendor ID 1f24-Subdevice ID 2011,1*4
PCIE Card	Network Card,25 Gigabit,64bit,SFP28(without Optical Transceiver), 2 Ports,PCIE 3.0 x8-14e4-16d7-2,No Driver CD
OCP Card	Manufactured Board-JDM,Public Module,BC53ETHI,XC386 OCP3.0 Ethernet Adapter-25GE(BCM57414)-Dual Port-SFP28(without Optical Module)-PCIE 3.0 X8-Vendor ID 14e4-Device ID 16d7-2-Subvendor ID 1f24-Subdevice ID 2013,1*4
PCIE Card	Network Card,100 Gigabit,64bit,QSFP28,2 ports,PCIE 4.0 x16-14e4-1750-2, No Driver CD,OCP
HBA Card	Other Cards,HBA Card LPe31002-AP,FC Double Ports-16Gb/s,PCIE 3.0 x8-Vendor ID 10DF-Device ID E300-2-Subvendor ID 10DF-Subdevice ID E310,English doc,1pcs short bracket,half width half length
HBA Card	Other Cards,HBA Card LPE35002-AP,FC Double Ports--32Gb/s, PCIE 4.0 x8-10df-f400-2,Chinese and English doc,half width half length
GPU Card	GPU Card,NVIDIA L20 GPU Accelerator,PN:900-2G133-00A0-000 / 48GB GDDR6 Memory / 864GB/s Memory Bandwidth /PCIE 4.0 x16-10DE-26BA-1 /350W,No NVLink,English doc,Dual slot,Passive
GPU Card	GPU Card,NVIDIA L2 GPU Accelerator,PN:900-2G193-0030-000/ 24GB GDDR6 Memory/ 300GB/s peak Memory Bandwidth/ PCIE 4.0 x16-10DE-27B6-1,72W/ HHHL, single-slot/Passive cooling,English doc, No Cable
GPU Card	GPU Card,NVIDIA RTX 6000D PCIe GPU,PN:900-2G153-0030-000 / 84GB GDDR7 Memory / 1398GB/s Memory Bandwidth /PCIE 5.0 x16-10DE-2BB9-1 /600W,English doc,Dual slot,Passive,GENERIC
GPU Card	GPU Card,NVIDIA RTX 6000D PCIe GPU,PN:900-2G153-0030-200 / 84GB GDDR7 Memory / 1398GB/s Memory Bandwidth /PCIE 5.0 x16-10DE-2BB9-1 /600W,English doc,Dual slot,Passive,SHORT BRACKET

DPU Card	Network Card,200Gb/s,64bit,QSFP112,2 Ports,PCIE 5.0 X16-15b3-a2dc| c2d5-3,No Driver CD,NVIDIA BlueField B3220 Crypto Disabled-Single-Slot-32GB DDR5-FHHL
Super capacitor module	Super capacitor module,64mm*51mm*13.1mm, Wire mounting,split from 08170002,NA,7600uF,5h
PSU	Function Module,AC&HVDC , Server Platinum 900W AC power supply
PSU	Function Module,AC&HVDC , Server Platinum 1500W AC power supply
PSU	Function Module,AC&HVDC , Server Platinum 2000W AC power supply
PSU	Function Module,AC&HVDC , Server Titanium 900W AC power supply
PSU	Function Module,AC&HVDC , Server Titanium 2000W AC power supply
PSU	Function Module,AC&HVDC , Server Titanium 3000W AC power supply
PSU	Function Module, DC , Server Platinum 1200W DC power supply
TPM CARD	Function Module,TS200-2280,BC11TPMC02,TPM2.0 Card(SPI), China Dedicated
TPM CARD	Function Module,TS200-2280,BC11TPMA02,TPM2.0 Card(SPI), Overseas Dedicated
Battery	Original Battery,Li-(CFx)n battery,3V,0.19Ah,Round,D20*3.2mm

Annex Ⅲ Typical Configuration of Product

Board list		
Board Name	Description	Qty
BC15HBBA	Manufactured Board,2288H V7,BC15HBBA,8*2.5" SAS/ SATA HDD backplane,1*2	1
BC15FDCA	Manufactured Board,2288H V7,BC15FDCA, Fan Board 4*8080+/8038+,1*3	1
BC15RCIA	Manufactured Board,2288H V7,BC15RCIA, Right Customer Interface Board,5*2	1
BC82LCIA	Manufactured Board,TaiShan 2280 V2,BC82LCIA, Left Customer Interface,4*2	1
BC16MBSC	Manufactured Board,BC16MBSC, 1288 V8/2288 V8 Server motherboard,1*1	1
Subassembly list		
Subassembly Name	Description	
BMC Card	Manufactured Board,BC26SMMAA,DC-SCM Hi1711 BMC Card,1*1	
FAN	Fan Assembly,10.8V,13.2V,80*80*56,80mm,8PIn,120W,130CFM	
Plastic parts	Plastic,2120Y139_DRAEN.ASM,Fan box,FusionServer 7.9.0	
Riser Card	Manufactured Board,BC16PRUK, IO1/IO2 Riser1-2*x16(2*PCIe5.0x8)(Slot2/3)+1CEM(Slot1),1*2	
PCIE Card	Manufactured Board,Public Module,CN21ITGG1,XP330 Ethernet Adapter, 10Gb Optical Interface(Intel X710),2-Port,SFP+(without Optical Transceiver), PCIE 3.0 X8-Vendor ID 8086-Device ID 1572-2-Subvendor ID 1f24-Subdevice ID 2003,1*2	
OCP Card	Manufactured Board-JDM,Public Module,BC53ETHI, XC386 OCP3.0 Ethernet Adapter-25GE(BCM57414)-Dual Port-SFP28 (without Optical Module)-PCIE 3.0 X8-Vendor ID 14e4-Device ID 16d7-2-Subvendor ID 1f24-Subdevice ID 2013,1*4	
OCP Card	Network Card,100 Gigabit,64bit,QSFP28,2 ports, PCIE 4.0 x16-14e4-1750-2,No Driver CD,OCP	
PSU	Function Module,AC&HVDC , Server Platinum 1500W AC power supply	
Battery	Original Battery,Li-(CFx)n battery,3V,0.19Ah,Round,D20*3.2mm	

END